LNJ826W86RA

Surface Mounting Chip LED

UTSS Type

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Power dissipation	P_{D}	55	mW	
Forward current	I_{F}	20	mA	
Pulse forward current *	I_{FP}	60	mA	
Reverse voltage	V _R	4	V	
Operating ambient temperature	T _{opr}	-30 to +85	°C	
Storage temperature	T _{stg}	-40 to +100	°C	

Note) *: The condition of I_{FP} is duty 10%, pulse width 10 ms.

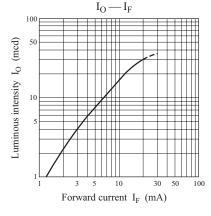
■ Lighting Color

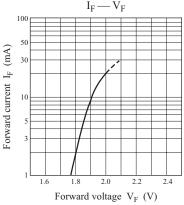
Soft Orange

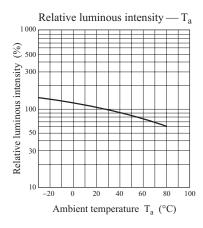
■ Electro-Optical Characteristics $T_a = 25$ °C±3°C

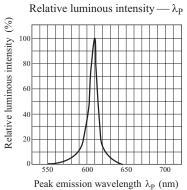
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I _O	$I_F = 10 \text{ mA}$	13.5	16.9		mcd
Reverse current	I_R	$V_R = 4 V$			100	μΑ
Forward voltage	V _F	$I_F = 10 \text{ mA}$		1.92	2.50	V
Peak emission wavelength	λ_{P}	$I_F = 10 \text{ mA}$		610		nm
Dominant emission wavelength	λ_{d}	$I_F = 10 \text{ mA}$	600	605	610	nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$		15		nm

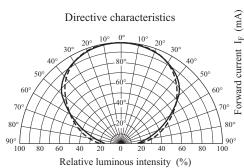
Note) Be careful of the product destruction by static electricity.

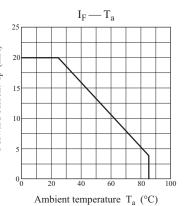






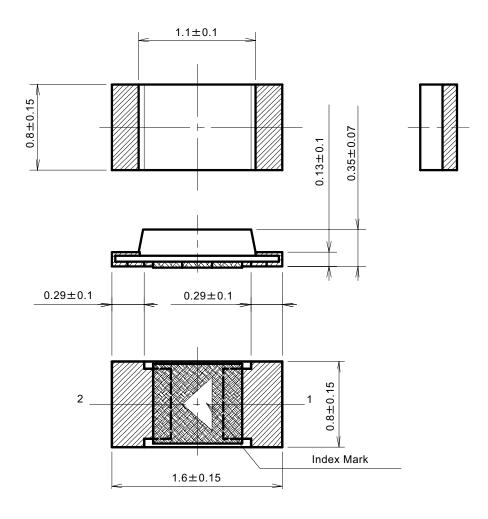






■ Package (Unit: mm)

KLTFTN2K2600



- Pin name
 - 1: Anode
 - 2: Cathode

2 SHD00604CEK

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